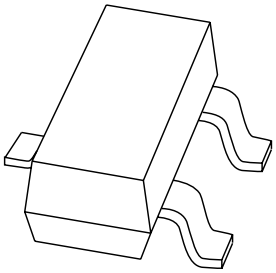
DATA SHEET



BCX70 series
NPN general purpose transistors

Product data sheet
Supersedes data of 1999 Apr 15

2004 Jan 16

NXP founded by Philips

NPN general purpose transistors BCX70 series

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 45 V).

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

NPN transistor in a SOT23 plastic package.
PNP complements: BCX71 series.

MARKING

TYPE NUMBER	MARKING CODE(1)
BCX70G	AG*
BCX70H	AH*
BCX70J	AJ*
BCX70K	AK*

Note

1. * = p : Made in Hong Kong.
   * = t : Made in Malaysia.
   * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

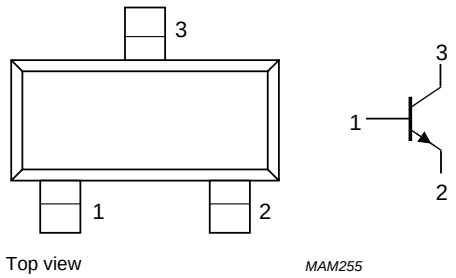


Fig.1 Simplified outline (SOT23) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCX70G	–	plastic surface mounted package; 3 leads	SOT23
BCX70H			
BCX70J			
BCX70K			

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

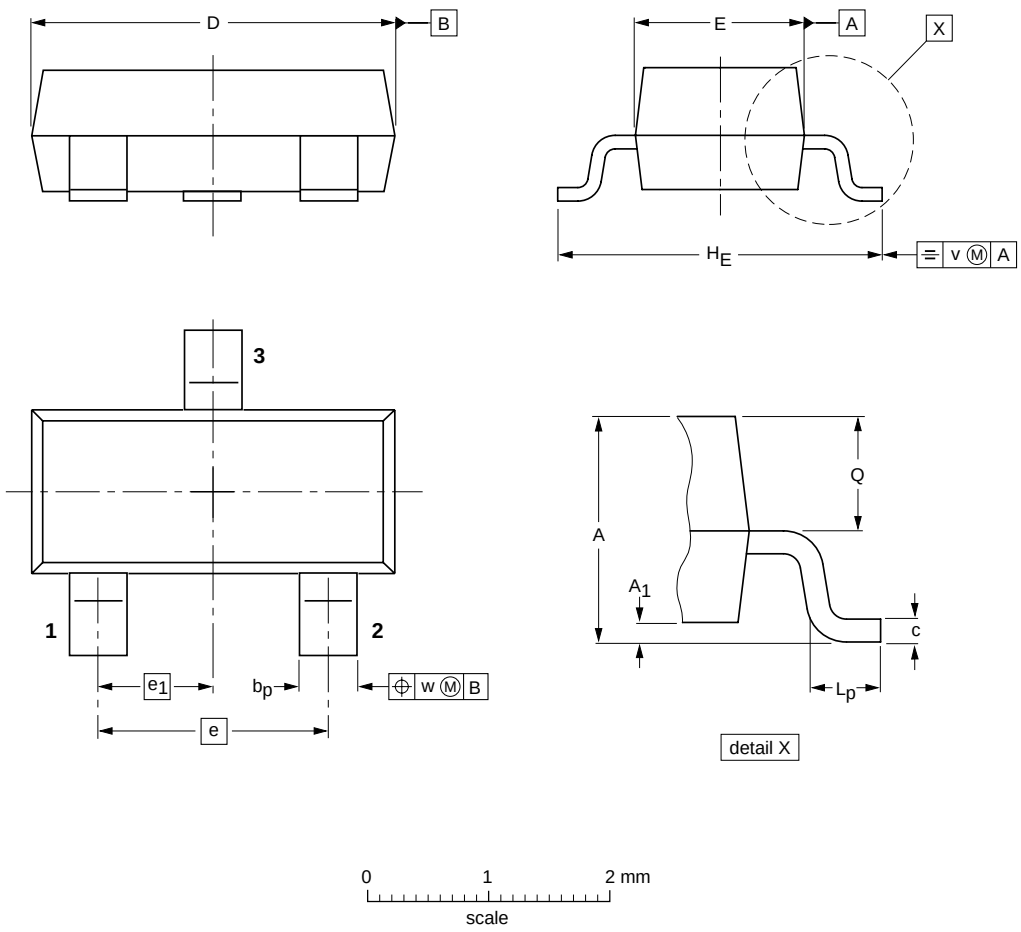
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = 45 V	–	–	20	nA
		I_E = 0; V_{CB} = 45 V; T_{amb} = 150 °C	–	–	20	μA
I_{EBO}	emitter cut-off current	I_C = 0; V_{EB} = 4 V	–	–	20	nA
h_{FE}	DC current gain	I_C = 10 μA; V_{CE} = 5 V				
	BCX70G		–	–	–	
	BCX70H		40	–	–	
	BCX70J		30	–	–	
	BCX70K		100	–	–	
	DC current gain	I_C = 2 mA; V_{CE} = 5 V				
	BCX70G		120	–	220	
	BCX70H		180	–	310	
	BCX70J		250	–	460	
	BCX70K		380	–	630	
	DC current gain	I_C = 50 mA; V_{CE} = 1 V				
	BCX70G		50	–	–	
	BCX70H		70	–	–	
	BCX70J		90	–	–	
	BCX70K		100	–	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 0.25 mA	50	–	350	mV
		I_C = 50 mA; I_B = 1.25 mA	100	–	550	mV
V_{BEsat}	base-emitter saturation voltage	I_C = 10 mA; I_B = 0.25 mA	600	–	850	mV
		I_C = 50 mA; I_B = 1.25 mA	700	–	1050	mV
V_{BE}	base-emitter voltage	I_C = 10 μA; V_{CE} = 5 V	–	520	–	mV
		I_C = 2 mA; V_{CE} = 5 V	550	650	750	mV
		I_C = 50 mA; V_{CE} = 1 V	–	780	–	mV
C_c	collector capacitance	I_E = i_e = 0; V_{CB} = 10 V; f = 1 MHz	–	1.7	–	pF
C_e	emitter capacitance	I_C = i_c = 0; V_{EB} = 0.5 V; f = 1 MHz	–	11	–	pF
f_T	transition frequency	I_C = 10 mA; V_{CE} = 5 V; f = 100 MHz; note 1	100	250	–	MHz
F	noise figure	I_C = 200 μA; V_{CE} = 5 V; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz	–	2	6	dB

Note

1. Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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Printed in The Netherlands R75/04/pp7 Date of release: 2004 Jan 16 Document order number: 9397 750 12408

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